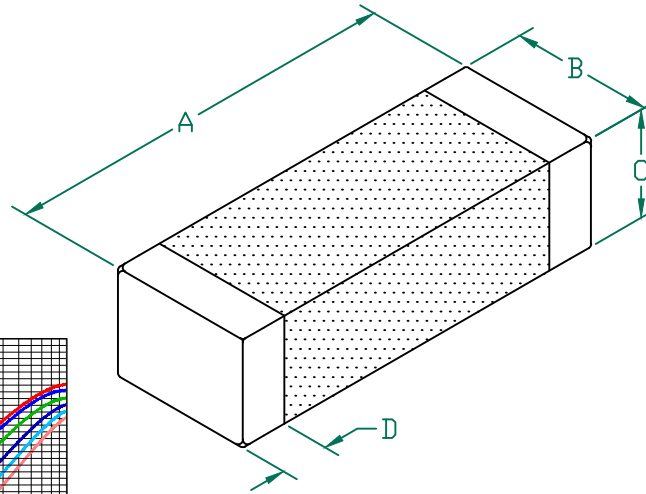


DM3312X101R-10

PHYSICAL DIMENSIONS:

A	8.50 [.335]	+ 0.20 [.008]
B	3.05 [.120]	+ 0.20 [.008]
C	2.28 [.090]	+ 0.20 [.008]
D	0.89 [.035]	+ 0.20 [.008]



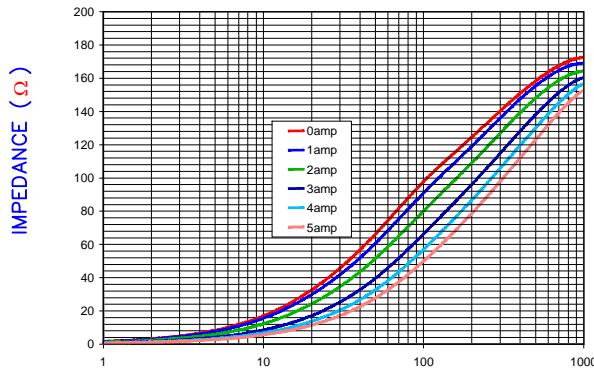
ELECTRICAL CHARACTERISTICS:

Z @ 100MHz (Ω)	DCR (Ω)	Rated Current
Nominal	100	
Minimum	75	
Maximum	125	10,000 mA

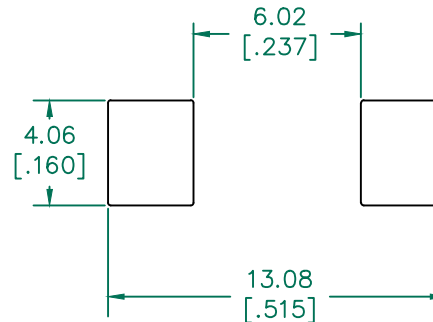
NOTES: UNLESS OTHERWISE SPECIFIED

1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS, 13" REELS, 2,500 PCS/REEL.
2. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
3. TERMINATION FINISH IS 100% TIN.
4. OPERATING TEMPERATURE TEMP: $-40^{\circ}\text{C} \sim +125^{\circ}\text{C}$ (INCLUDING SELF-HEATING)

Z vs FREQUENCY
IMPEDANCE UNDER DC BIAS

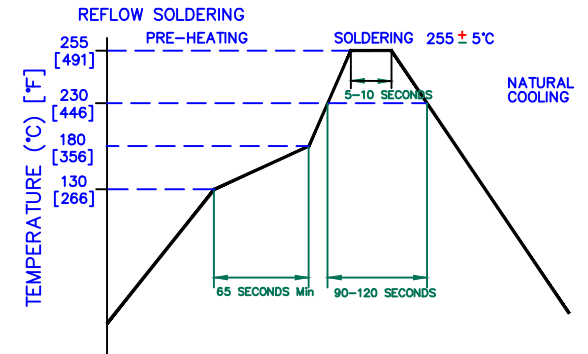


LAND PATTERNS FOR REFLOW SOLDERING



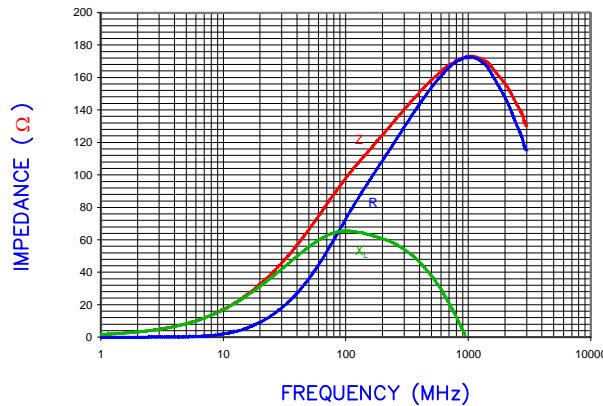
(For wave soldering, add 0.762 [.030] to this dimension.)

RECOMMENDED SOLDERING CONDITIONS



FREQUENCY (MHz)

|Z|, R, AND X vs. FREQUENCY



FREQUENCY (MHz)

Z R X_L

AGILENT E4991A RF Impedance/Material Analyzer
HP 16194A Test Fixture. TEST REF. 3435



DIMENSIONS ARE IN mm [INCHES]				This print is the property of Laird Tech. and is loaned in confidence subject to return upon request and with the understanding that no copies shall be made without the written consent of Laird Tech. All rights to design or invention are reserved.	
F	OPERATING TEMPERATURE UPDATE LAIRD LOGO AND REFLOW CURVE	08/05/13	QU		
E	UPDATE COMPANY LOGO	05/22/09	JRK		
D	UPDATE COMPANY LOGO	1/10/08	JRK		
C	CHANGE TOLERANCE ON DIMENSION D	08/29/06	JRK		
B	INCREASE D DIMENSION TO 0.035 REM NOTE 2 CHG LANDPATTERN DIMENSION	03/20/06	JRK		
A	ORIGINAL DRAFT	02/09/04	TMB	PROJECT/PART NUMBER: DM3312X101R-10	
REV	DESCRIPTION	DATE	INT	DATE:	02/09/04
				SCALE:	-
				SHEET:	1 of 1